



Schottky Diodes

Features

- High frequency operation
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications



MBRL2060CT

■ Thermal Characteristics $T_a=25$ Unless otherwise specified

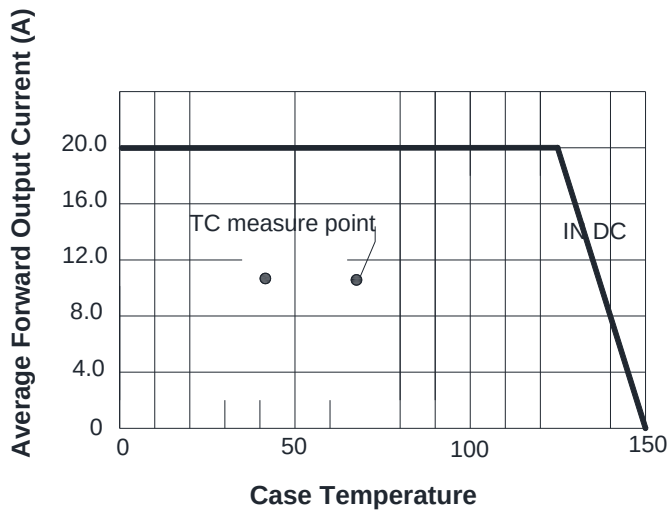
PARAMETER		SYMBOL	UNIT	MBRL2060CT
Thermal Resistance	Between junction and case	$R_{\theta J-C}$	$^{\circ}W$	2.0

■ Ordering Information (Example)

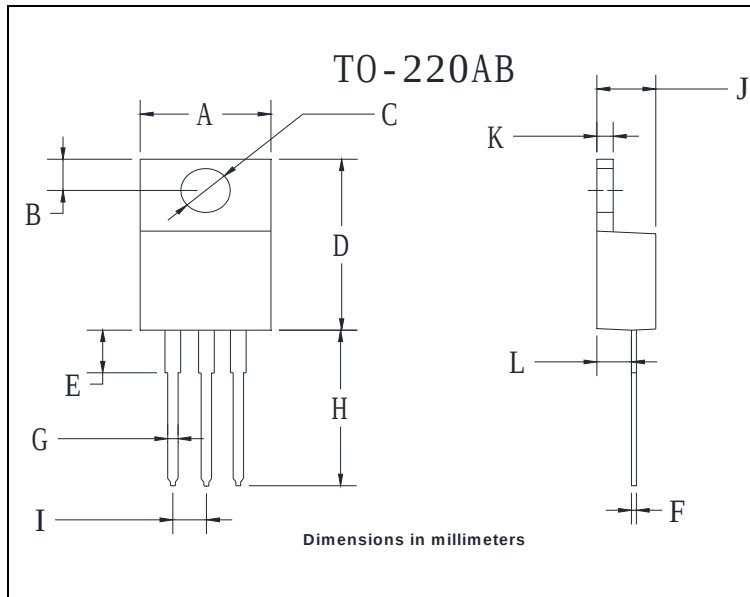
PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MBRL2060CT	Approximate 1.9	50	1000	5000	Tube

■ Characteristics (Typical)

FIG1: I_o - T_c Curve



■Outline Dimensions



Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and